

L3 ANSWER 10 OF 10 REGISTRY COPYRIGHT 2006 ACS on STN
 RN 111-41-1 REGISTRY
 ED Entered STN: 16 Nov 1984
 CN Ethanol, 2-[(2-aminoethyl)amino]- (6CI, 8CI, 9CI) (CA INDEX NAME)
 OTHER NAMES:
 CN (β-Hydroxyethyl)ethylenediamine
 CN (2-Hydroxyethyl)ethylenediamine
 CN 1-(2-Hydroxyethylamino)-2-aminoethane
 CN 2-(2'-Aminoethylamino)ethanol
 CN 2-(2-Aminoethylamino)ethanol
 CN 2-(2-Hydroxyethylamino)ethylamine
 CN A-EA
 CN Amino Alcohol EA
 CN N-(β-Aminoethyl)ethanolamine
 CN N-(β-Hydroxyethyl)-1,2-ethanediamine
 CN N-(β-Hydroxyethyl)ethylenediamine
 CN N-(2'-Hydroxyethyl)ethylenediamine
 CN N-(2-Aminoethyl)ethanolamine
 CN N-(2-Hydroxyethyl)-1,2-ethanediamine
 CN N-(2-Hydroxyethyl)-1,2-ethylenediamine
 CN N-(2-Hydroxyethyl)ethylenediamine
 CN N-(Hydroxyethyl)ethylenediamine
 CN N-Hydroxyethyl-1,2-ethanediamine
 CN NSC 461
 FS 3D CONCORD
 DR 51251-98-0
 MF C4 H12 N2 O
 CI COM
 LC STN Files: ANABSTR, BEILSTEIN*, BIOSIS, CA, CAOLD, CAPLUS, CASREACT, CHEMCATS, CHEMINFORMRX, CHEMLIST, CHEMSAFE, CIN, CSCHM, DETHERM*, DIPPR*, GMELIN*, HSDB*, IFICDB, IFIPAT, IFIUDB, MEDLINE, MSDS-OHS, NIOSHTIC, PROMT, PS, RTECS*, SCISEARCH, SPECINFO, SYNTHLINE, TOXCENTER, USPAT2, USPATFULL
 (*File contains numerically searchable property data)
 Other Sources: DSL**, EINECS**, TSCA**
 (**Enter CHEMLIST File for up-to-date regulatory information)



PROPERTY DATA AVAILABLE IN THE 'PROP' FORMAT

1932 REFERENCES IN FILE CA (1907 TO DATE)
 573 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA
 1934 REFERENCES IN FILE CAPLUS (1907 TO DATE)
 33 REFERENCES IN FILE CAOLD (PRIOR TO 1967)

(FILE 'HOME' ENTERED AT 12:25:53 ON 06 APR 2006)

FILE 'REGISTRY' ENTERED AT 12:32:44 ON 06 APR 2006

FILE 'REGISTRY' ENTERED AT 12:35:02 ON 06 APR 2006

L1 0 S 2-2-AMINOETHYLAMINO-ETHANOL/CN
L2 14113 S AMINO AND ETHYL AND ETHANOL AND NC=1
L3 10 S AMINOETHYLAMINO AND L2
L4 1 S 111-41-1/RN

FILE 'CAPLUS, USPATFULL' ENTERED AT 12:37:38 ON 06 APR 2006

L5 2700 S L4

FILE 'REGISTRY' ENTERED AT 12:38:06 ON 06 APR 2006

L6 1 S DIETHYLHYDROXYLAMINE/CN

FILE 'CAPLUS, USPATFULL' ENTERED AT 12:38:37 ON 06 APR 2006

L7 1258 S L6

=> s 17 and 15

L8 13 L7 AND L5

=> d 1-13

L8 ANSWER 1 OF 13 CAPLUS COPYRIGHT 2006 ACS on STN

AN 2005:731719 CAPLUS

DN 143:214170

TI Antifouling agent and antifouling method

IN Taketsuji, Koji; Nakajima, Sadao

PA Hakuto Co., Ltd., Japan

SO Jpn. Kokai Tokkyo Koho, 9 pp.

CODEN: JKXXAF

DT Patent

LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2005213369	A2	20050811	JP 2004-21853	20040129
PRAI	JP 2004-21853		20040129		
OS	MARPAT 143:214170				

L8 ANSWER 2 OF 13 CAPLUS COPYRIGHT 2006 ACS on STN

AN 2004:609913 CAPLUS

DN 141:149480

TI Cleaning compositions containing hydroxylamine derivatives and processes using same for residue removal in microcircuitry fabrication

IN Zhou, De-ling; Qiao, Jing; Lee, Shihying; Patel, Bakul P.; Hon, Becky Min

PA USA

SO U.S. Pat. Appl. Publ., 44 pp., Cont.-in-part of U.S. Ser. No. 162,679.

CODEN: USXXCO

DT Patent

LA English

FAN.CNT 16

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 2004147420	A1	20040729	US 2003-689620	20031022
	US 5334332	A	19940802	US 1992-911102	19920709
	US 6110881	A	20000829	US 1996-654007	19960528
	US 6319885	B1	20011120	US 2000-603693	20000626
	US 2002052301	A1	20020502	US 2001-988545	20011120
	US 2003228990	A1	20031211	US 2002-162679	20020606
	US 6825156	B2	20041130		
	US 2006003909	A1	20060105	US 2005-181747	20050715
PRAI	US 1992-911102	A2	19920709		
	US 1993-78657	B1	19930621		
	US 1996-654007	A1	19960528		
	US 2000-603693	A1	20000626		
	US 2001-988545	A2	20011120		

US 2002-162679 A2 20020606
US 1990-610044 A2 19901105
US 2004-826286 A1 20040419
OS MARPAT 141:149480

L8 ANSWER 3 OF 13 CAPLUS COPYRIGHT 2006 ACS on STN
AN 2004:371040 CAPLUS
DN 140:392676
TI Aqueous phosphoric acid compositions for cleaning organic and plasma
etched residues from semiconductor devices
IN Daviot, Jerome; Reid, Christopher; Holmes, Douglas
PA EKC Technology, Inc., USA
SO PCT Int. Appl., 25 pp.
CODEN: PIXXD2
DT Patent
LA English
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 2004037962	A2	20040506	WO 2003-US33500	20031021
	WO 2004037962	A3	20040923		
	W:	AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW			
	RW:	GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG			
	US 2004137736	A1	20040715	US 2003-688900	20031021
	EP 1576072	A2	20050921	EP 2003-777786	20031021
	R:	AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK			
	JP 2006503972	T2	20060202	JP 2005-501654	20031021
PRAI	US 2002-419968P	P	20021022		
	US 2002-430365P	P	20021203		
	WO 2003-US33500	W	20031021		
OS	MARPAT 140:392676				

L8 ANSWER 4 OF 13 CAPLUS COPYRIGHT 2006 ACS on STN
AN 2003:971700 CAPLUS
DN 140:21992
TI Semiconductor process residue removal composition and process
IN Lee, Wai Mun; Ip, Katy; Dinh, Xuan-Dung; Maloney, David John
PA EKC Technology, Inc., USA
SO U.S. Pat. Appl. Publ., 42 pp.
CODEN: USXXCO
DT Patent
LA English
FAN.CNT 16

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 2003228990	A1	20031211	US 2002-162679	20020606
	US 6825156	B2	20041130		
	CN 1465687	A	20040107	CN 2002-141901	20020629
	WO 2003104185	A1	20031218	WO 2002-US20840	20020701
	W:	AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZM, ZW			
	RW:	GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG			
	AU 2002315510	A1	20031222	AU 2002-315510	20020701

EP 1509490 A1 20050302 EP 2002-742372 20020701
 R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT,
 IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, SK
 JP 2005528660 T2 20050922 JP 2004-511255 20020701
 US 2004147420 A1 20040729 US 2003-689620 20031022
 US 2005090416 A1 20050428 US 2004-995239 20041124
 PRAI US 1992-911102 A2 19920709
 US 1993-78657 B1 19930621
 US 1996-654007 A1 19960528
 US 2000-603693 A1 20000626
 US 2001-988545 A2 20011120
 US 2002-162679 A 20020606
 WO 2002-US20840 W 20020701
 OS MARPAT 140:21992

RE.CNT 14 THERE ARE 14 CITED REFERENCES AVAILABLE FOR THIS RECORD
 ALL CITATIONS AVAILABLE IN THE RE FORMAT

L8 ANSWER 5 OF 13 CAPLUS COPYRIGHT 2006 ACS on STN
 AN 2003:335239 CAPLUS
 DN 138:347373
 TI Composition for cleaning semiconductor devices
 IN Itano, Mitsushi; Kezuka, Takehiko
 PA Daikin Industries, Ltd., Japan
 SO PCT Int. Appl., 28 pp.
 CODEN: PIXXD2

DT Patent
 LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 2003035815	A1	20030501	WO 2002-JP10976	20021023
	W: CN, KR, US				
	RW: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, SK, TR				
	JP 2003129089	A2	20030508	JP 2001-326948	20011024
	EP 1447440	A1	20040818	EP 2002-770236	20021023
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, FI, CY, TR, BG, CZ, EE, SK				
	CN 1575331	A	20050202	CN 2002-821177	20021023
	US 2005003977	A1	20050106	US 2004-493432	20040423
PRAI	JP 2001-326948	A	20011024		
	WO 2002-JP10976	W	20021023		

OS MARPAT 138:347373

RE.CNT 18 THERE ARE 18 CITED REFERENCES AVAILABLE FOR THIS RECORD
 ALL CITATIONS AVAILABLE IN THE RE FORMAT

L8 ANSWER 6 OF 13 CAPLUS COPYRIGHT 2006 ACS on STN
 AN 2001:578597 CAPLUS
 DN 135:124156
 TI Bactericide combinations in detergents
 IN Elsmore, Richard; Houghton, Mark Phillip
 PA Robert McBride Ltd., UK
 SO Brit. UK Pat. Appl., 53 pp.
 CODEN: BAXXDU

DT Patent
 LA English

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	GB 2354771	A1	20010404	GB 1999-23253	19991001
PRAI	GB 1999-23253		19991001		

L8 ANSWER 7 OF 13 CAPLUS COPYRIGHT 2006 ACS on STN
 AN 1999:658550 CAPLUS
 DN 131:293311
 TI Photoresist removing composition containing corrosion prevention agent
 IN Fujimoto, Hideki; Ogawa, Shoji
 PA Toray Fine Chemicals KK, Japan
 SO Jpn. Kokai Tokkyo Koho, 5 pp.

. CQDEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 11282176	A2	19991015	JP 1998-98494	19980326
PRAI	JP 1998-98494		19980326		

L8 ANSWER 8 OF 13 CAPLUS COPYRIGHT 2006 ACS on STN
AN 1993:589503 CAPLUS
DN 119:189503
TI Mutual solubilities: water + cyclic amines, water + alkanolamines, and
water + polyamines
AU Stephenson, Richard M.
CS Dep. Chem. Eng., Univ. Connecticut, Storrs, CT, 06268, USA
SO Journal of Chemical and Engineering Data (1993), 38(4), 634-7
CODEN: JCEAAX; ISSN: 0021-9568
DT Journal
LA English

L8 ANSWER 9 OF 13 CAPLUS COPYRIGHT 2006 ACS on STN
AN 1959:38644 CAPLUS
DN 53:38644
OREF 53:6854f
TI Compositions for image transfer in photography
IN Land, Edwin H.; Blout, Elkan R.; Cohen, Saul G.; Green, Milton; Tracy,
Helen J.; Woodward, Robert B.
PA Polaroid Corp.
DT Patent
LA Unavailable
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 2857276		19581021	US 1954-470802	19541123
	DE 1068118			DE	

L8 ANSWER 10 OF 13 USPATFULL on STN
AN 2005:4872 USPATFULL
TI Composition for cleaning
IN Itano, Mitsushi, Settsu-shi, JAPAN
Kezuka, Takehiko, Settsu-shi, JAPAN
PI US 2005003977 A1 20050106
AI US 2004-493432 A1 20040423 (10)
WO 2002-JP10976 20021023
PRAI JP 2001-326948 20011024
DT Utility
FS APPLICATION

LN.CNT 867

INCL INCLM: 510/175.000

NCL NCLM: 510/175.000

IC [7]

ICM C11D001-00

IPCI C11D0001-00 [ICM,7]

IPCR C11D0001-38 [I,C]; C11D0001-40 [I,A]; C11D0003-43 [I,A];

C11D0003-43 [I,C]; C11D0007-22 [I,C]; C11D0007-32 [I,A];

C11D0007-50 [I,A]; C11D0007-50 [I,C]; C11D0011-00 [I,A];

C11D0011-00 [I,C]; G03F0007-42 [I,A]; G03F0007-42 [I,C]

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L8 ANSWER 11 OF 13 USPATFULL on STN
AN 2004:190647 USPATFULL
TI Cleaning compositions containing hydroxylamine derivatives and processes
using same for residue removal
IN Zhou, De-Ling, Sunnyvale, CA, UNITED STATES
Qiao, Jing, Fremont, CA, UNITED STATES
Lee, Shihying, Fremont, CA, UNITED STATES
Patel, Bakul P., Pleasanton, CA, UNITED STATES
Hon, Becky Min, Milpitas, CA, UNITED STATES

PI ,US 2004147420 A1 20040729
AI US 2003-689620 A1 20031022 (10)
RLI Continuation-in-part of Ser. No. US 2002-162679, filed on 6 Jun 2002,
PENDING Continuation-in-part of Ser. No. US 2001-988545, filed on 20 Nov
2001, PENDING Continuation of Ser. No. US 2000-603693, filed on 26 Jun
2000, GRANTED, Pat. No. US 6319885 Continuation of Ser. No. US
1996-654007, filed on 28 May 1996, GRANTED, Pat. No. US 6110881
Continuation of Ser. No. US 1993-78657, filed on 21 Jun 1993, ABANDONED
Continuation-in-part of Ser. No. US 1992-911102, filed on 9 Jul 1992,
GRANTED, Pat. No. US 5334332

DT Utility

FS APPLICATION

LN.CNT 2859

INCL INCLM: 510/176.000

NCL NCLM: 510/176.000

NCLS: 257/E21.255; 257/E21.304; 257/E21.309; 257/E21.313; 257/E21.577;
257/E21.589

IC [7]

ICM C11D001-00

IPCI C11D0001-00 [ICM,7]

IPCR B24B0037-04 [I,A]; B24B0037-04 [I,C]; C09D0009-00 [I,A];
C09D0009-00 [I,C]; C11D0003-20 [I,A]; C11D0003-20 [I,C];
C11D0003-26 [I,C]; C11D0003-30 [I,A]; C11D0003-34 [I,A];
C11D0003-34 [I,C]; C11D0003-43 [I,A]; C11D0003-43 [I,C];
C11D0007-22 [I,C]; C11D0007-26 [I,A]; C11D0007-32 [I,A];
C11D0007-34 [I,A]; C11D0007-50 [I,A]; C11D0007-50 [I,C];
C11D0011-00 [I,A]; C11D0011-00 [I,C]; C23G0001-02 [I,C];
C23G0001-10 [I,A]; C23G0001-14 [I,C]; C23G0001-20 [I,A];
G03F0007-42 [I,A]; G03F0007-42 [I,C]; H01L0021-02 [I,C];
H01L0021-306 [N,A]; H01L0021-311 [I,A]; H01L0021-321 [I,A];
H01L0021-3213 [I,A]; H01L0021-70 [I,C]; H01L0021-768 [I,A]

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L8 ANSWER 12 OF 13 USPATFULL on STN

AN 2004:178569 USPATFULL

TI Aqueous phosphoric acid compositions for cleaning semiconductor devices

IN Daviot, Jerome, Glasgow, UNITED KINGDOM

Reid, Christopher, Glasgow, UNITED KINGDOM

Holmes, Douglas, Bridge of Weir, UNITED KINGDOM

PI US 2004137736 A1 20040715

AI US 2003-688900 A1 20031021 (10)

PRAI US 2002-419968P 20021022 (60)

US 2002-430365P 20021203 (60)

DT Utility

FS APPLICATION

LN.CNT 940

INCL INCLM: 438/690.000

NCL NCLM: 438/690.000

IC [7]

ICM H01L021-302

ICS H01L021-461

IPCI H01L0021-302 [ICM,7]; H01L0021-461 [ICS,7]

IPCR C11D0007-02 [I,C]; C11D0007-06 [I,A]; C11D0007-08 [I,A];

C11D0007-22 [I,C]; C11D0007-32 [I,A]; C11D0011-00 [I,A];

C11D0011-00 [I,C]

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L8 ANSWER 13 OF 13 USPATFULL on STN

AN 2003:325008 USPATFULL

TI Semiconductor process residue removal composition and process

IN Lee, Wai Mun, Fremont, CA, UNITED STATES

Ip, Katy, Oakland, CA, UNITED STATES

Dinh, Xuan-Dung, San Jose, CA, UNITED STATES

Maloney, David John, Pleasanton, CA, UNITED STATES

PI US 2003228990 A1 20031211

US 6825156 B2 20041130

AI US 2002-162679 A1 20020606 (10)

DT Utility

FS APPLICATION

LN. CNT 3040

INCL INCLM: 510/202.000

INCLS: 510/212.000; 510/499.000

NCL NCLM: 510/176.000; 510/202.000

NCLS: 134/001.300; 134/002.000; 134/038.000; 134/040.000; 510/175.000;
510/245.000; 510/255.000; 510/212.000; 510/499.000

IC [7]

ICM C11D001-00

IPCI C11D0001-00 [ICM,7]

IPCI-2 C11D0007-26 [ICM,7]; C11D0007-50 [ICS,7]

IPCR C11D0003-26 [I,C]; C11D0003-30 [I,A]; C11D0007-22 [I,C];

C11D0007-32 [I,A]; C11D0011-00 [I,A]; C11D0011-00 [I,C];

G03F0007-42 [I,A]; G03F0007-42 [I,C]

CAS INDEXING IS AVAILABLE FOR THIS PATENT.